

MULTILAYERED SUBSTRATE FOR SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

10 A multilayered substrate for a semiconductor device,
which has a multilayered substrate body formed of a
plurality sets of a conductor layer and an insulation
layer, and having a face for mounting a semiconductor
element thereon and another face for external connection
terminals, the face for mounting a semiconductor device
being provided with pads through which the substrate is
15 connected to a semiconductor element to be mounted
thereon, and the face for external connection terminals
being provided with pads through which the substrate is
connected to an external electrical circuit, wherein a
reinforcing sheet is respectively joined to the face for
20 mounting a semiconductor element thereon and the face for
external connection terminals of the multilayered
substrate body.